

06-30-2009

RECORDATION FORM COV  
PATENTS ON



103565355

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):  
TAKESHI FUKUDA (05/19/2009), RYO  
MUKAIYAMA (05/19/2009), TAKUO IKEDA  
(05/20/2009), AND KO KUSANAGI  
(05/19/2009)

Execution Date(s): in parentheses after inventor name

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other

2. Name and address of receiving party(ies)

Name: SONY CORPORATION

Internal Address:

Street Address:

1-7-1 Konan, Minato-ku  
Tokyo 108-0075  
JAPAN

City:

State:

Country:

Zip:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Dennis M. Smid, Esq.  
LERNER, DAVID, LITTENBERG,  
KRUMHOLZ & MENTLIK, LLP

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Fax Number: (908) 654-0415

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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card  
☒ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers 06/29/2009 06/29/2009 06/29/2009 06/29/2009  
Expiration Date 06/29/2009 06/29/2009 06/29/2009 06/29/2009  
b. Deposit Account Number 40.00 12-1095  
Authorized User Name Dennis M. Smid, Esq.

9. Signature:

Signature

June 16, 2009

Date

Dennis M. Smid, Esq. - 34,930

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

5

Docket Number: \_\_\_\_\_

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING METHOD AND INFORMATION PROCESSING PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all prior rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_.

This assignment executed on the dates indicated below.

Takeshi FUKUDA

Name of first or sole inventor

May 19, 2009  
Execution date of U.S. Patent Application

Chiba, Japan

Residence of first or sole inventor

Takeshi Fukuda

Signature of first or sole inventor

May 19, 2009  
Date of this assignment

Ryo MUKAIYAMA

Name of second inventor

May, 19, 2009

Execution date of U.S. Patent Applicat

Tokyo, Japan

Residence of second inventor

Ryo Mukaiyama

Signature of second inventor

May, 19, 2009

Date of this assignm

Takuo IKEDA

Name of third inventor

Execution date of U.S. Patent Applicat

Tokyo, Japan

Residence of third inventor

Signature of third inventor

Date of this assignm

Ko KUSANAGI

Name of fourth inventor

May 19, 2009

Execution date of U.S. Patent Applicat

Tokyo, Japan

Residence of fourth inventor

Ko Kusanagi

Signature of fourth inventor

May 19, 2009

Date of this assignm

Name of fifth inventor

Execution date of U.S. Patent Applicat

Residence of fifth inventor

Signature of fifth inventor

Date of this assignm

Docket Number: \_\_\_\_\_

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING METHOD AND INFORMATION PROCESSING PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all prior rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention and applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require or prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date in this application in the spaces that follow: Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_.

This assignment executed on the dates indicated below.

Takeshi FUKUDA

Name of first or sole inventor

Execution date of U.S. Patent Application

Chiba, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

Ryo MUKAIYAMA

Name of second inventor

Execution date of U.S. Patent Applic

Tokyo, Japan

Residence of second inventor

Signature of second inventor

Date of this assign

Takuo IKEDA

Name of third inventor

May 20. 2009

Execution date of U.S. Patent Applic

Tokyo, Japan

Residence of third inventor

Takuo Ikeda

Signature of third inventor

May 20. 2009

Date of this assign

Ko KUSANAGI

Name of fourth inventor

Execution date of U.S. Patent Applic

Tokyo, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assign

Name of fifth inventor

Execution date of U.S. Patent Applic

Residence of fifth inventor

Signature of fifth inventor

Date of this assign

PATENT

RECORDED: 06/16/2009

REEL: 022891 FRAME: 0750